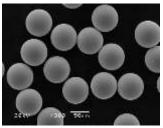


PRESS RELEASE

SHENMAO Exhibits at IMAPS System in Package June 27-28, 2017 Introducing 3 New Semiconductor Packaging Fluxes









SHENMAO Technology, Inc. introduces New Generation Ultra Tacky Flux SMF-WC52 applied in the Flip Chip dipping process. Its high tacky property keeps Chip in place during reflow for excellent soldering performance, while creating outstanding solder joint strength.

SHENMAO introduces New Generation Ultra Low Residue Liquid Flux SMF-B51 with superior spray uniformity, excellent soldering performance and a wide process window for Chip Scale and Fan Out Wafer Level Packaging.

SHENMAO introduces New WLCSP/FOWLP Ball Attach Flux SMF-WB51 for excellent ball attach soldering due to its highly suitable wide reflow profile and designed for slump resistance to prevent bridging. Applicable for lead free and lead containing alloys, its higher viscosity, medium Ti index with stable slump characteristics present great printability and excellent stencil life, uniform dipping value in Flux Dip/Pin Transfer and Solder Ball Drop to create excellent Ball Hight and Coplanarity.

SHENMAO BGA Solder Spheres for PBGA, CBGA, TBGA, CSP and Flip Chip Assemblies are made by UMT (Ultra Micron Technology) from highly pure metals produced to various exact Alloy compositions using Piezoelectric Droplet Jet Technology in high volumes to accurate diameter uniformity, bright shiny surface finishes and high-quality sphericity. Various diameters (0.76 to 0.05 mm Dia.- 0.045 and 0.040 mm Dia. are in development) are available in SAC305, SAC405 and SAC1205 Alloys at affordable low cost from 10 worldwide SHENMAO locations.

As the World's Major Solder Materials Provider, **SHENMAO** produces SMT Solder Paste, Wave Solder Bar, Cored Solder Wire and Flux, Solder Preforms, Semiconductor Packaging Solder Spheres, Wafer Bumping Solder Paste, Dipping Flux and PV Ribbon.

For more information, please contact:

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